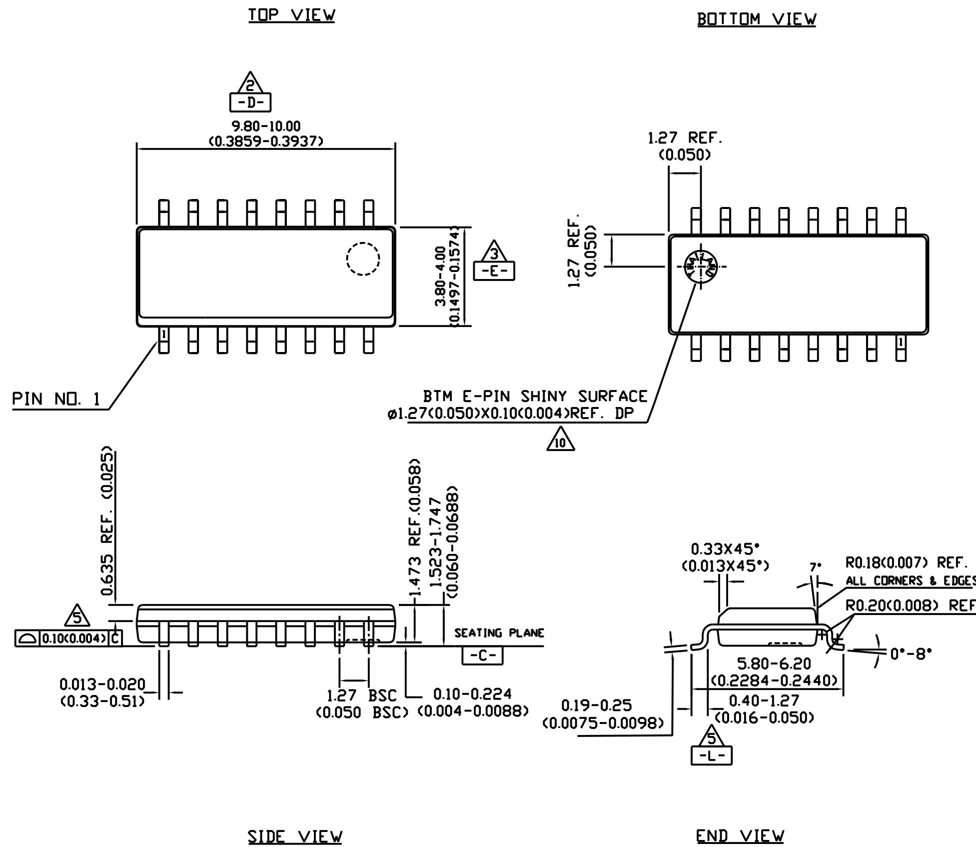
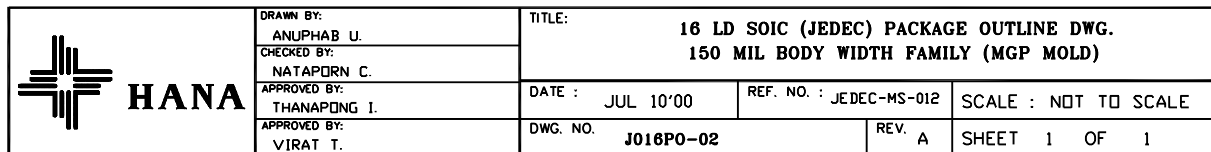
REV	DESCRIPTION	DATE
A	ORIGINAL ISSUE	JUL 10'00



NOTES:
1. DIMENSIONING & TOLERANCING PER ANSI.Y14.5M-1982.
2. DIMENSION "D" DOES NOT INCLUDE MOLD FLASH,PROTRUSIONS OR GATE BURRS.MOLD FLASH,PROTRUSION OR GATE BURRS SHALL NOT EXCEED 0.15MM(0.006") PER SIDE.
3. DIMENSION "E" DOES NOT INCLUDE INTER-LEAD FLASH OR PROTRUSION,INTER-LEAD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.25MM(0.010") PER SIDE.
4. "L" IS A LENGTH OF TERMINAL FOR SOLDERING TO SUBSTATE.
5. FORMED LEAD SHALL BE PLANED WITH RESPECT TO ONE ANOTHER WITHIN 0.10MM(0.004") AT SEATING PLANE"C"
6. BODY FINISH : 21-24 CHARMILLES.
7. CONTROLLING DIMENSION : MILLIMETER CONVERTED INCH DIMENSION ARE NOT NECESSARILY EXACT.
8. LEAD FINISH IS ELECTROPLATING WITH A THICKNESS OF 300 - 800 MICROINCH.
9. CHARACTER HEIGHT ON EJECTOR PIN IS 0.25MM(0.0098").
10. RAISEDED CHARACTER NOT TO PROTRUDE BEYOND SURFACE OR PACKAGE BODY.



HANA	DRAWN BY: ANUPHAB U.	TITLE: 16 LD SOIC (JEDEC) PACKAGE OUTLINE DWG. 150 MIL BODY WIDTH FAMILY (MGP MOLD)			
	CHECKED BY: NATAPORN C.				
	APPROVED BY: THANAPONG I.	DATE : JUL 10'00	REF. NO. : JEDEC-MS-012		SCALE : NOT TO SCALE
	APPROVED BY: VIRAT T.	DWG. NO. J016PO-02		REV. A	SHEET 1 OF 1